Serial Number: 10/003,238 Filing Date: October 26, 2001

Title: ELECTRONIC ASSEMBLIES WITH FILLED NO-FLOW UNDERFILL (As Amended)

Assignee: Intel Corporation

IN THE SPECIFICATION

Please make the paragraph substitutions indicated below. The specific changes incorporated in the substitute paragraph are shown in the following marked-up version of the previously amended paragraph.

The paragraph beginning on page 8, line 24 is amended as follows:

Underfill 116 includes a filler having a plurality of particles 120 [[116]]. In an embodiment, the particles 116 are distributed substantially uniformly throughout the underfill 116. In an embodiment, the filler comprises an agent to reduce the CTE (coefficient of thermal expansion). The filler is selected from the group consisting of silica, silicon oxide, silicon dioxide, silicon nitride, aluminum oxide, and aluminum nitride. The filler can also be selected from the group comprising any ceramic oxide and any ceramic nitride.